## **MA27D300G**

### Silicon epitaxial planar type

For super high speed switching

#### ■ Features

- Small reverse current:  $I_R < 2 \mu A$  (at  $V_R = 30 \text{ V}$ )
- Optimum for high frequency rectification because of its short reverse recovery time t<sub>rr</sub>.

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	30	V
Repetitive peak reverse voltage	$V_{RRM}$	30	V
Forward current (Average)	I <sub>F(AV)</sub>	100	mA
Peak forward current	$I_{FM}$	200	mA
Non-repetitive peak forward	I <sub>FSM</sub>	1	A
surge current *			
Junction temperature	$T_{j}$	125	°C
Storage temperature	$T_{stg}$	-55 to +125	°C

Note) \*: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

#### Package

- Code
  - SSSMini2-F3
- Pin Name
  - 1: Anode
- 2: Cathode

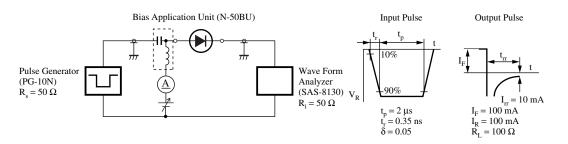
#### ■ Marking Symbol: 8N

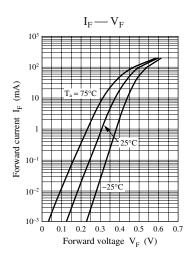
#### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

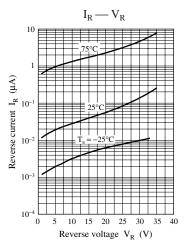
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V <sub>F1</sub>	$I_F = 10 \text{ mA}$		0.38	0.44	V
	$V_{F2}$	$I_F = 100 \text{ mA}$		0.51	0.58	V
Reverse current	I <sub>R1</sub>	$V_R = 10 \text{ V}$			0.3	μΑ
	$I_{R2}$	$V_R = 30 \text{ V}$			2	μΑ
Terminal capacitance	C <sub>t</sub>	$V_R = 0 \text{ V, } f = 1 \text{ MHz}$		9		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 100 \text{ mA}$		1		ns
		$I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$				

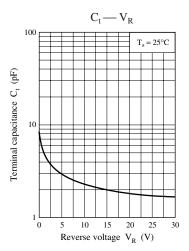
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

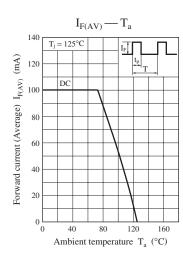
- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 250 MHz
- 4. \*: t<sub>rr</sub> measurement circuit







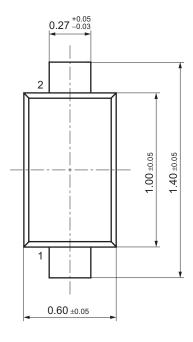


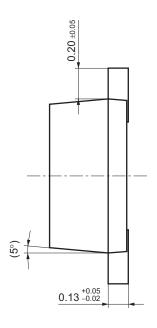


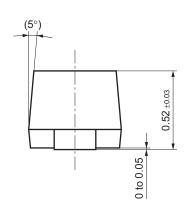
2 SKH00167AED

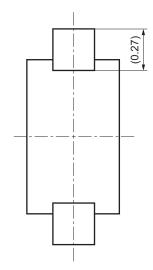
## SSSMini2-F3

Unit: mm









SKH00167AED 3

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